

Product Change Notice (PCN Tracking Number: EE-QR-221208-01)

Version: 2

Renesas Product Typ		ALL Customers					
		RA2L1 series, QFN and LQFP package products (refer to last page for complete product list)					
Description of Chang	ge: Addition of wa	Addition of wafer-fabrication and chip-assembly factories					
Reason for Change:	To ensure sta	ble production supply					
Identification:	Identifiable via	a production history data from the packi	ng label or trace code				
Schedules:	Sample delive Reliability rep Requested ap	deadline: e/o Mar. 2023 b/o May 2023 (upon requestor): b/o Aug. 2023 (upon requestor): e/o Aug. 2023 ementation b/o Oct. 2023 onwards					
Anticipated Impact:	Quality & Reli Specification	ability: No impact & Characteristic: No impact					
Doc. No.:	EE-QC-PCN-	CR-22-0230					
Internal Reference:	MCP-AC-22-0	0050					
In case of any question	, please contact:						
	TITLE	E-mail	PHONE No.				
	TITLE Staff Engineer	E-mail farhad.banihashemi@renesas.com	PHONE No. +49-211-6503-1844				
Farhad Banihashemi Düsseldorf, 22.02.2023 Customer Resp (please fill in and retu acknowledge acceptable inacceptable (pls. o not applicable Note: Acknowledgemental approved. If timely acknowledge accept of this PCN in PCN within 90 days of	Staff Engineer ONSE: rn by e-mail, fax or mail omment) Phone / nt must be received by nowledgement is provident which to make any obthe receipt of the PCN to	farhad.banihashemi@renesas.com ail) ompany: Position:	l consider the change as ave 90 days from the date make objections to this anges as approved. If				



Details of Change:

	Current fab			Additional fabs (parallel production)		
	Wafer fab	Assembly	Sort	Wafer fab	Assembly	Sort
Case1	Kawashiri	Greatek	KYEC	Kawashiri	Greatek	KYEC
				PSMC		
Case2	Kawashiri	RSB	RSB	Kawashiri	RSB	RSB
				PSMC	Greatek	KYEC

[#1] Factory names indicated as BOLD letters, will be added on the parallel production path.

1) Case1: QFN package products

Wafer fab: Powerchip Semiconductor Manufacturing Corporation (PSMC) addition

2) Case2: LQFP package products

Wafer fab: Powerchip Semiconductor Manufacturing Corporation (PSMC) addition

Assembly: Greatek Electronics Inc. (Greatek) addition Sort: King Yuan Electronics Corp. (KYEC) addition

(Remark for Case2: Greatek products to be shipped only via full-carton or T&R.)

1) Wafer-fabrication: Renesas Semiconductor Manufacturing Co., Ltd., Kawashiri factory

Chip-assembly: Renesas Semiconductor (Beijing) Co., Ltd (RSB)

Package types: LQFP 7x7mm 48pin, 10x10mm 64pin

2) Wafer fabrication factory addition: Powerchip Semiconductor Manufacturing Corporation (PSMC) Assembly factory addition: Greatek Electronics Inc.(Greatek)

3) Specification differences:

Wafer process: sufficiently equivalent process was ported from Kawashiri factory. Assembly materials: Lead-frame, Die-mount paste, and Mold-resin are certificated at each facility

4) Package outline:

No change on the foot-print geometry. Please refer the package outline drawings and the geometry comparison tables.

5) Marking:

Marking characters appears slightly different in the font type

DIVC	size		Pin-	thick	Fab addition (this time)			Current fabs			
PKG	[mm]	pins	pitch [mm]	ness [mm]	WP	Assembly	Sort	WP	Assembly	Sort	
LQFP	7x7	48	0.5	1.4	PSMC	Greatek	KYEC	Kawashiri	RSB	RSB	
LQFP	10x10	64	0.5	1.4	PSMC	Greatek	KYEC	Kawashiri	RSB	RSB	

Kawashiri: Renesas Semiconductor Manufacturing Company Co., Ltd. Kawashiri Factory

PSMC: Powerchip Semiconductor Manufacturing Corporation

RSB: Renesas Semiconductor (Beijing) Co.. Ltd

KYEC: King Yuan Electronics Co., Ltd Greatek: Greatek Electronics Inc.



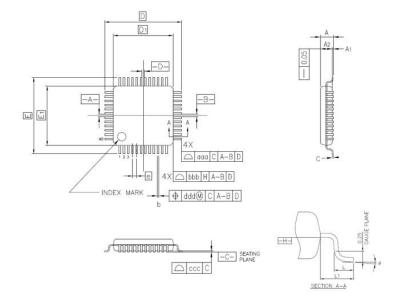
Change Overview:

Ite	ems	This time	Current		
Wafer	process	Kawashiri, PSMC	Kawashiri		
Ass	embly	Greatek	RSB		
S	Sort	KYEC	RSB		
Package	Outline	Slight differenc	es (see p.3~p.6)		
Lead frame	Material	No dif	ference		
Lead frame	Inner lead shape	Shape difference	ence (see p.7)		
Die mount	Material	Ag epoxy paste D *	Ag epoxy paste A *		
Bonding wire	Material	No difference:	Cu (Pd coating)		
Mold resin	Material	Epoxy resin D * (halogen-free)	Epoxy resin A * (halogen-free)		
Plating	Material	No dif	ference		
Marking	Font	Font type diffe	rence (see p.7)		
Marking	Digit number	No difference			
Packing	Tray / T&R	No dif	ference		
Storage conditions	after opening	No dif	ference		

^{*} Factory certified materials, there are differences however no impact on reliability or characteristics.

7mm×7mm 0.5mm pitch 48pin LFQFP package outline(Greatek)

RENESAS Code: PLQP0048KL-A



Reference	Dimension in Millimeters					
Symbol	Min.	Nom.	Max.			
А	35	=	1.60			
At	0.05	-	0,15			
A ₂	1.35	1.40	1.45			
D	-	9.00	-			
D1	10-	7.00	1577			
E	_	9.00	_			
E ₁	-	7.00	-			
N	-	48	-			
е	-	0.50	1			
ь	0.17	0.22	0.27			
С	0.09	-	0.20			
θ	0.	3.5*	7*			
L	0.45	0.60	0.75			
L ₁	-	1.00	-			
aaa	794	-	0.20			
bbb	13.55	-	0.20			
ccc	-	<u>-</u>	0.08			
ddd		-	0.08			

Nom

7.0

7.0

1.4

9.0

0.20

3.5

0.6

7.1

7,1

9.2

9.2 1.7

0.15

0.27

0.20

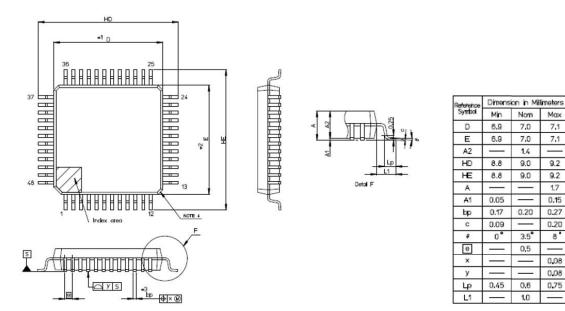
8 0.08 0.08

0.75



7mm×7mm 0.5mm pitch 48pin LFQFP package outline(RSB)

RENESAS Code: PLQP0048KB-B



Comparison: 7mm×7mm 0.5mm pitch 48pin LFQFP package

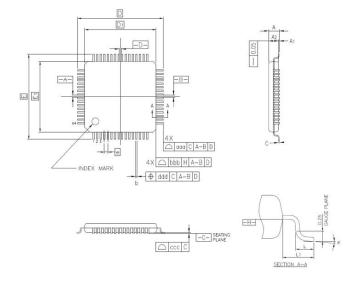
Greatek package symbols comply JEDEC standard.

Greatek	7x7mm 48pin LQFP			RSB	7x7mm 48pin LQFP			
Symbol	PL	QP0048KI	A	Symbol	PLQP0048KB-B			
	Dimens	ion in Mil	imeters		Dimens	ion in Mil	limeters	
	Min	Nom	Max	1	Min	Nom	Max	
Α	-	-	1.60	Α	-	-	1.70	
A1	0.05	-	0.15	A1	0.05	=1	0.15	
A2	1.35	1.40	1.45	A2	-	1.40	-	
D	-	9.00	100	HD	8.80	9.00	9.20	
D1	-	7.00		D	6.90	7.00	7.10	
E		9.00		HE	8.80	9.00	9.20	
E1	-	7.00	-	Е	6.90	7.00	7.10	
N	1=	48	-	-	-	-	51	
е	-	0.50	8.5	е	0.53	0.50	-	
b	0.17	0.22	0.27	bp	0.17	0.20	0.27	
С	0.09	-:	0.20	С	0.09	-	0.20	
θ	0°	3.5°	7°	θ	0°	3.5°	8°	
L	0.45	0.60	0.75	Lp	0.45	0.60	0.75	
L1	-	1.00	85	L1	1.5	1.00	-	
aaa	-	-	0.20	-	-	-	-	
bbb	-	-	0.20	-		-	-	
CCC	.=		0.08	У	-	-	0.08	
ddd	-	-	0.08	Х	-	-	0.08	



10mm×10mm 0.5mm pitch 64pin LFQFP package outline(Greatek)

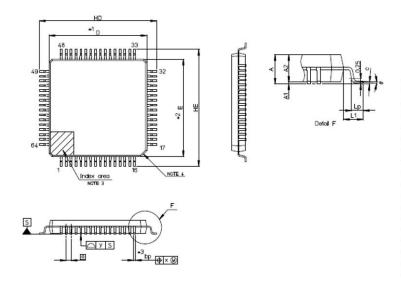
RENESAS Code: PLQP0064KL-A



Reference	Dimension in Millimeters					
Symbol	Min.	Nom.	Max.			
Α	-	1-1	1.60			
Α ₁	0.05	:-:	0.15			
A ₂	1.35	1.40	1.45			
D	_	12.00	-			
D1		10.00	-			
E	-	12.00				
E ₁	_	10.00	-			
N	_	64	1000			
е	=	0.50	-			
Ь	0.17	0.22	0.27			
С	0.09	-	0.20			
θ	0.	3.5*	7			
L	0.45	0.60	0.75			
L ₁	_	1.00	-			
aaa	-	1-1	0.20			
bbb	-	-	0.20			
ccc	_	-	0.08			
ddd	-	-	0.08			

10mm×10mm 0.5mm pitch 64pin LFQFP package outline(RSB)

RENESAS Code: PLQP0064KB-C



Reference	Dimension in Millimeters					
Symbol	Min	Nom	Max			
D	9.9	10.0	10.1			
Ε	9.9	10.0	10.1			
A2	—	1.4	_			
HD	11.8	12.0	12.2			
ΗE	11.8	12.0	12.2			
Α	_	_	1.7			
A1	0.05	_	0.15			
bp	0.15	0.20	0.27			
С	0.09		0.20			
e	0"	3.5	8.			
0	_	0,5	_			
×	_		0.08			
У	_	7	0.08			
Lp	0.45	0.6	0.75			
L1		1.0	_			



Comparison: 10mm×10mm 0.5mm pitch 64pin LFQFP package

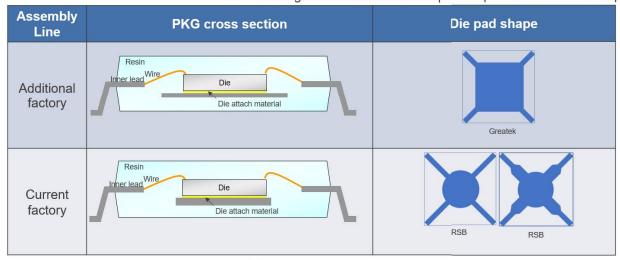
Greatek package symbols comply JEDEC standard.

Greatek	10x10mm 64pin LQFP			RSB	10x10mm 64pin LQFP			
Symbol	PLO	PLQP0064KL-A Symbol			PLO	PLQP0064KB-C		
	Dimens	ion in Mill	imeters		Dimens	ion in Mill	imeters	
	Min	Nom	Max		Min	Nom	Max	
Α	-	-	1.60	А	-	(-	1.70	
A1	0.05	-	0.15	A1	0.05	-	0.15	
A2	1.35	1.40	1.45	A2	-	1.40	-	
D		12.00	-	HD	11.80	12.00	12.20	
D1	-	10.00	-	D	9.90	10.00	10.10	
Е		12.00		HE	11.80	12.00	12.20	
E1	-	10.00	-	E	9.90	10.00	10.10	
N	-	64	-		-	-	=	
е	2	0.50	121	е	-	0.50	=	
b	0.17	0.22	0.27	bp	0.15	0.20	0.27	
С	0.09	1.5	0.20	С	0.09	-	0.20	
θ	0°	3.5°	7°	θ	0°	3.5°	8°	
L	0.45	0.60	0.75	Lp	0.45	0.60	0.75	
L1	-	1.00	120	L1	-	1.000	=	
aaa	-		0.20	(H	-	118	-	
bbb	-	1-	0.20	-		=	2	
CCC	-	-	0.08	У	-	-	0.08	
ddd	(=)	85	0.08	Х			0.08	



Package structure image

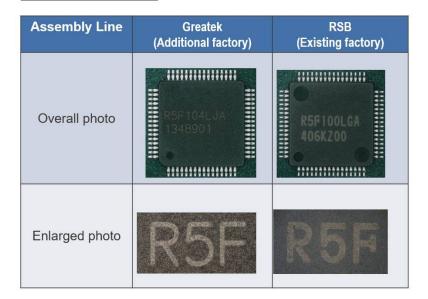
* Package cross-section and die pad shape are reference example



X There is no impact on the reliability with these die pad shapes

Marking visibility

XCharacters are reference example





4M changing points (Wafer process facility addition)

Full chip-design compatible wafer-fabrication-process was ported from Kawashiri factory.

ltem	Check Result	Judgement
Machine	Sufficiently compatible to produce the equivalent wafer-level structure and electrical characteristics	No risk
Method	Sufficiently compatible to produce the equivalent wafer-level structure and electrical characteristics	No risk
Man	Using operator certification system. Only certificated operator can work for the production.	No risk
Material	Sufficiently compatible to produce the equivalent wafer-level structure and electrical characteristics	No risk

4M changing points (Additional assembly factory)

Item	Check Result	Judgement
Machine	Despite some differences, the machines are equivalent to current fabrication machines. As well as similar existing products which show sufficient MP records, no problem found for the additional products.	No risk
Method	The same as the existing products.	No risk
Operator	Adopting operator certification system, only certificated operators are allowed for performing the production work.	No risk
Material	Only certificated materials are used. The products were certificated by specific reliability test as well as the existing products, no risk to be seen.	No risk



Affected Products:

		1	T	
Product P/N	Package		Product P/N	Package
R7FA2L1A93CNE#HA0	48pin QFN		R7FA2L1A92DFL#HA0	48pin LQFP
R7FA2L1A93CNE#BA0	48pin QFN		R7FA2L1A92DFL#BA0	48pin LQFP
R7FA2L1A93CNE#AA0	48pin QFN		R7FA2L1AB3CFL#HA0	48pin LQFP
R7FA2L1A92DNE#HA0	48pin QFN		R7FA2L1AB3CFL#BA0	48pin LQFP
R7FA2L1A92DNE#BA0	48pin QFN		R7FA2L1AB2DFL#HA0	48pin LQFP
R7FA2L1A92DNE#AA0	48pin QFN		R7FA2L1AB2DFL#BA0	48pin LQFP
R7FA2L1AB3CNE#HA0	48pin QFN		R7FA2L1A93CFM#HA0	64pin LQFP
R7FA2L1AB3CNE#BA0	48pin QFN		R7FA2L1A93CFM#BA0	64pin LQFP
R7FA2L1AB3CNE#AA0	48pin QFN		R7FA2L1A92DFM#HA0	64pin LQFP
R7FA2L1AB2DNE#HA0	48pin QFN		R7FA2L1A92DFM#BA0	64pin LQFP
R7FA2L1AB2DNE#BA0	48pin QFN		R7FA2L1AB3CFM#HA0	64pin LQFP
R7FA2L1AB2DNE#AA0	48pin QFN		R7FA2L1AB3CFM#BA0	64pin LQFP
R7FA2L1A93CFL#HA0	48pin LQFP		R7FA2L1AB2DFM#HA0	64pin LQFP
R7FA2L1A93CFL#BA0	48pin LQFP		R7FA2L1AB2DFM#BA0	64pin LQFP